

Destructive detectors for low energy ion beams

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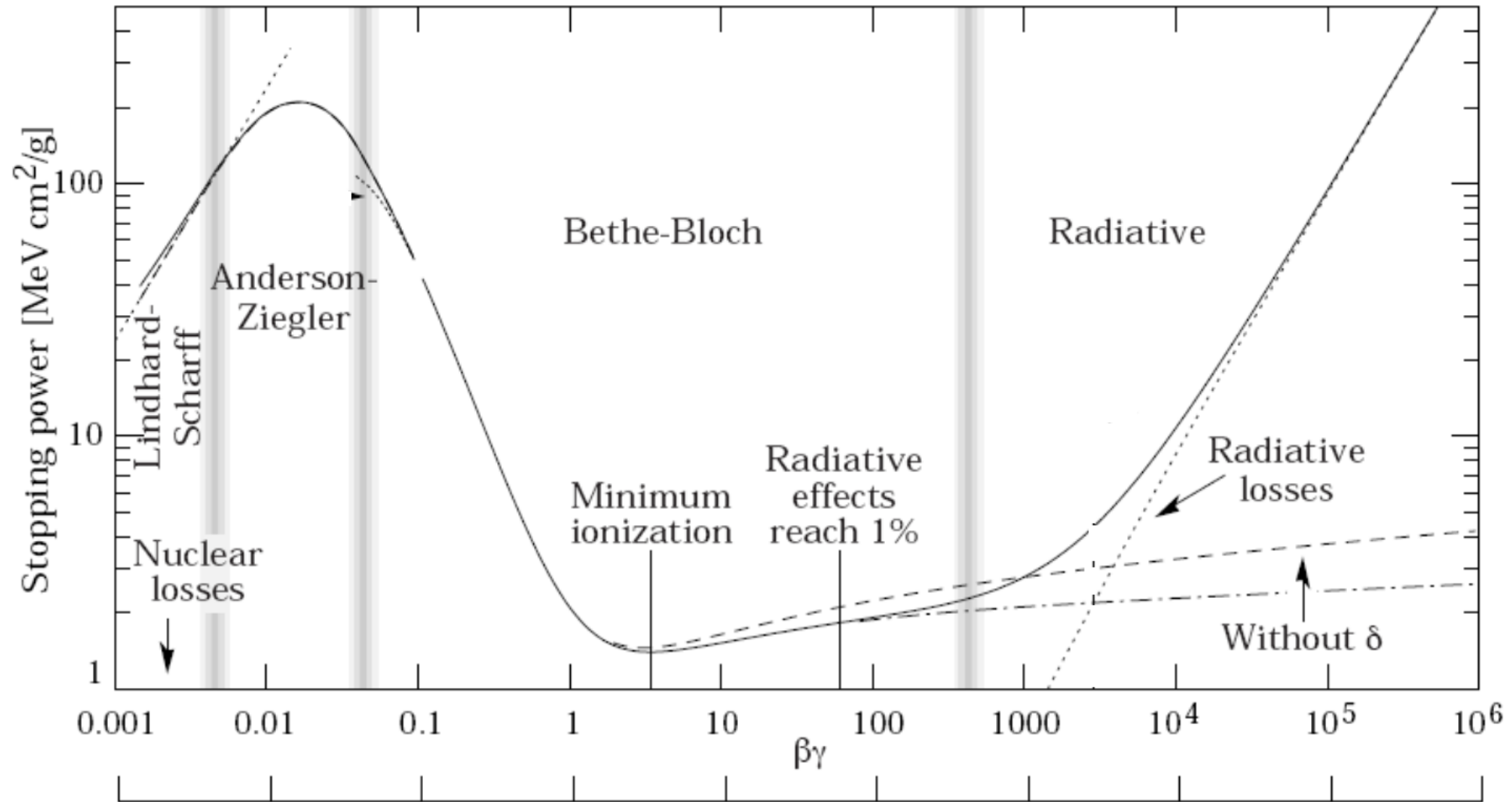
Outline

1. Interaction of particles with matter
2. Faraday Cup
3. Scicnillators/screen
4. Silicon detector

Interaction of particles with matter

- Ionization
 - Creation of electrons/ions pairs
 - *Secondary electron emission (low energy electrons)*
 - *Emission of photons (decay of excited states)*
- Elastic and Inelastic scattering
 - Dislocations
 - Production of secondary particles (high energy particles)
- Radiation
 - Cherenkov radiation
 - Bremsstrahlung
 - Optical transition radiation

Energy deposition

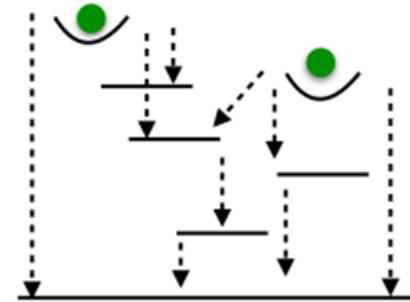
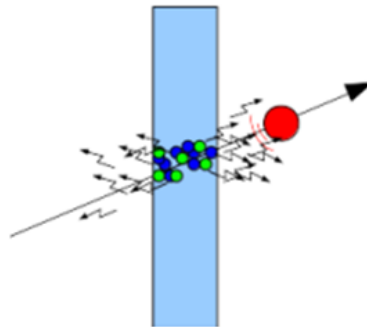
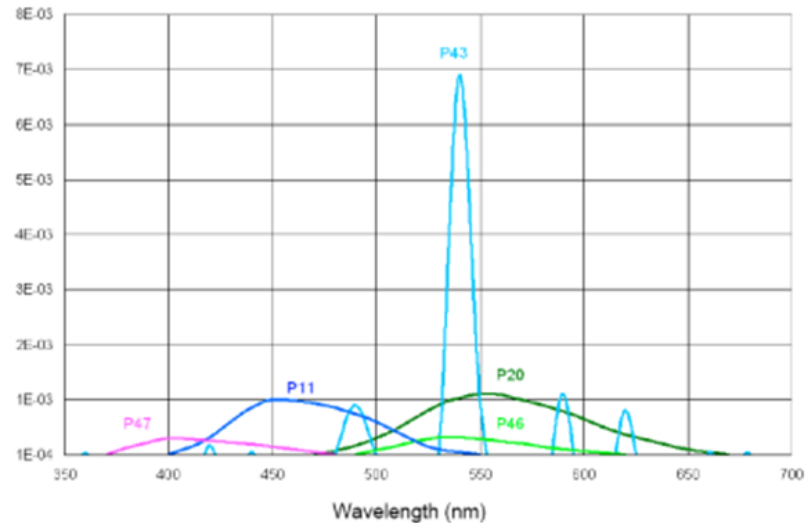


Scintillation

Type	Composition	Decay Time	
		Decay of Light Intensity from 90 % to 10 % in	from 10 % to 1 % in
P 43	Gd ₂ O ₂ S:Tb	1 ms	1,6 ms
P 46	Y ₃ Al ₅ O ₁₂ :Ce	300 ns	90 μs
P 47	Y ₂ SiO ₅ :Ce,Tb	100 ns	2,9 μs
P 20	(Zn,Cd)S:Ag	4 ms	55 ms
P 11	ZnS:Ag	3 ms	37 ms

- Linked to ionisation
- Photons are emitted by the de-excitation of atomic states populated by the passage of the particle
- Emission time ns to hours

Energy Conversion ((W/nm)/W)

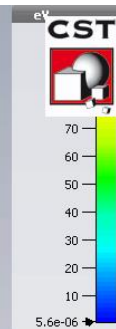
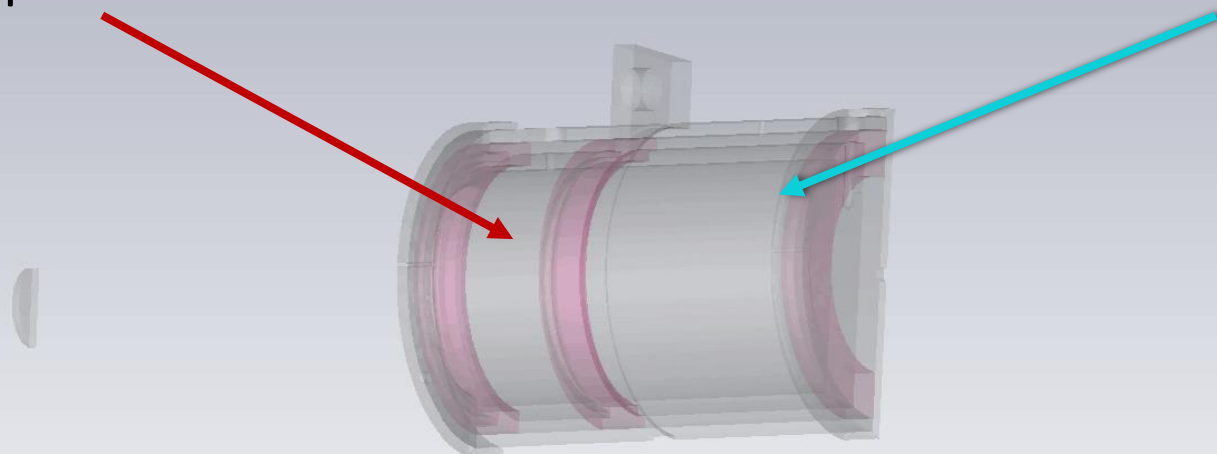


1MeV e⁻ on 5μm P43 yields ~ 60 ph.

Faraday Cup

Repeller

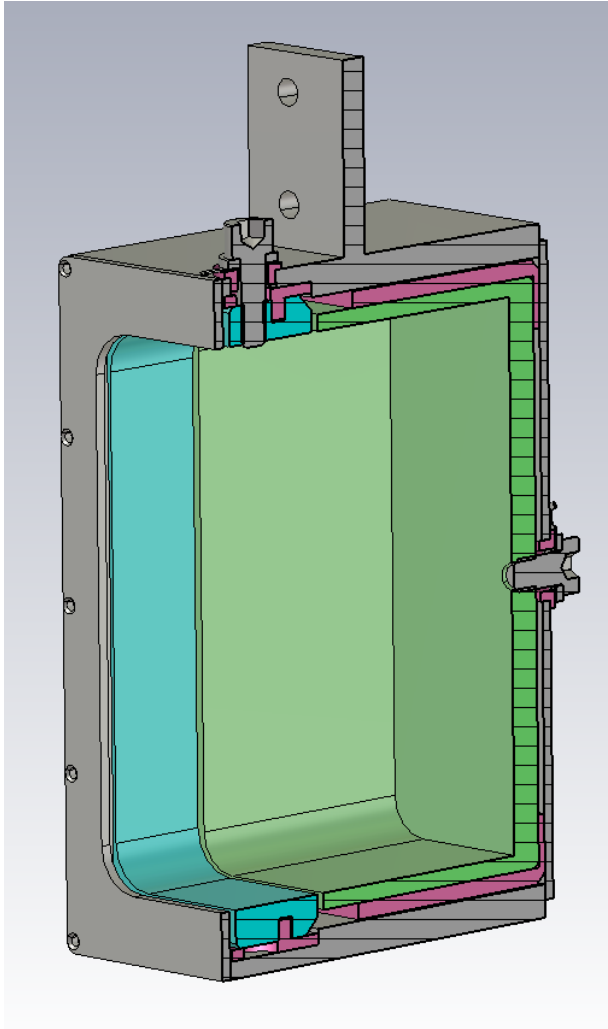
Collector



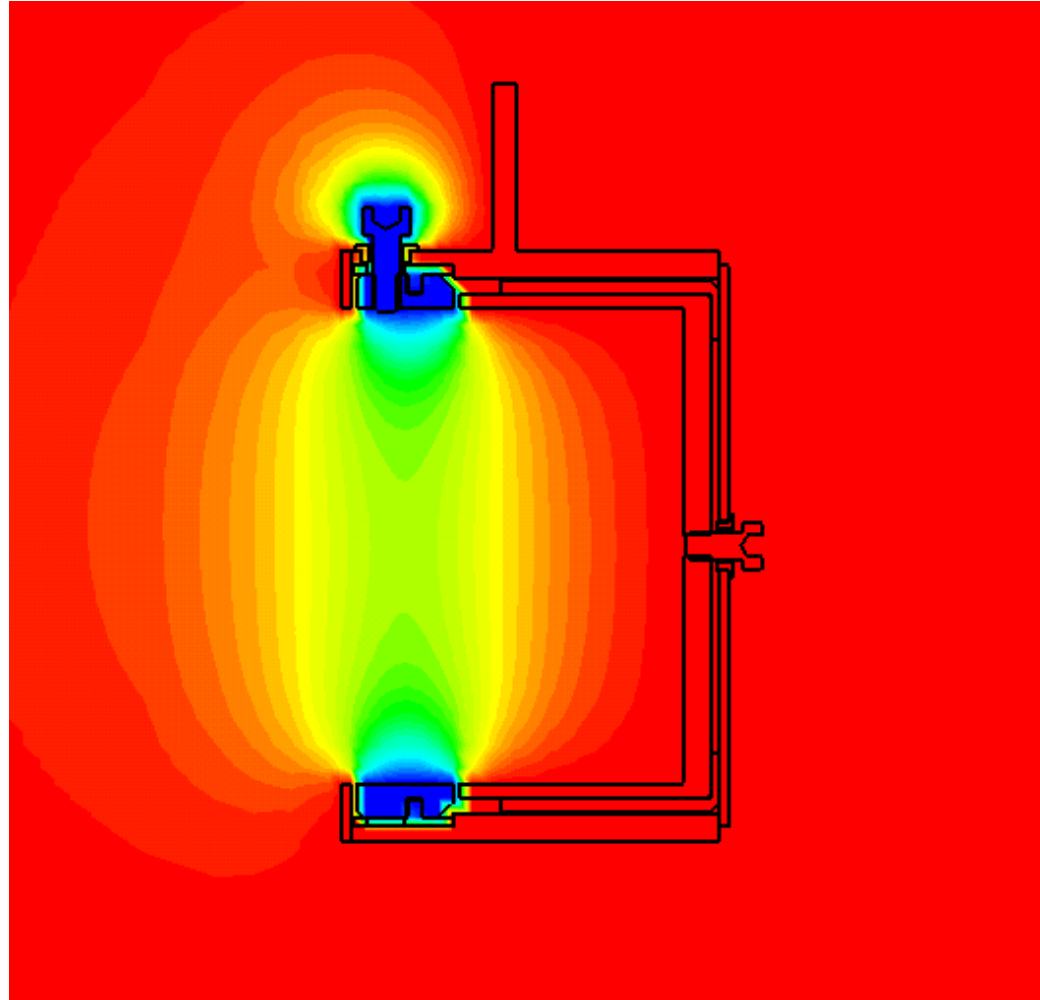
<1 pA detection



FC: Example 1



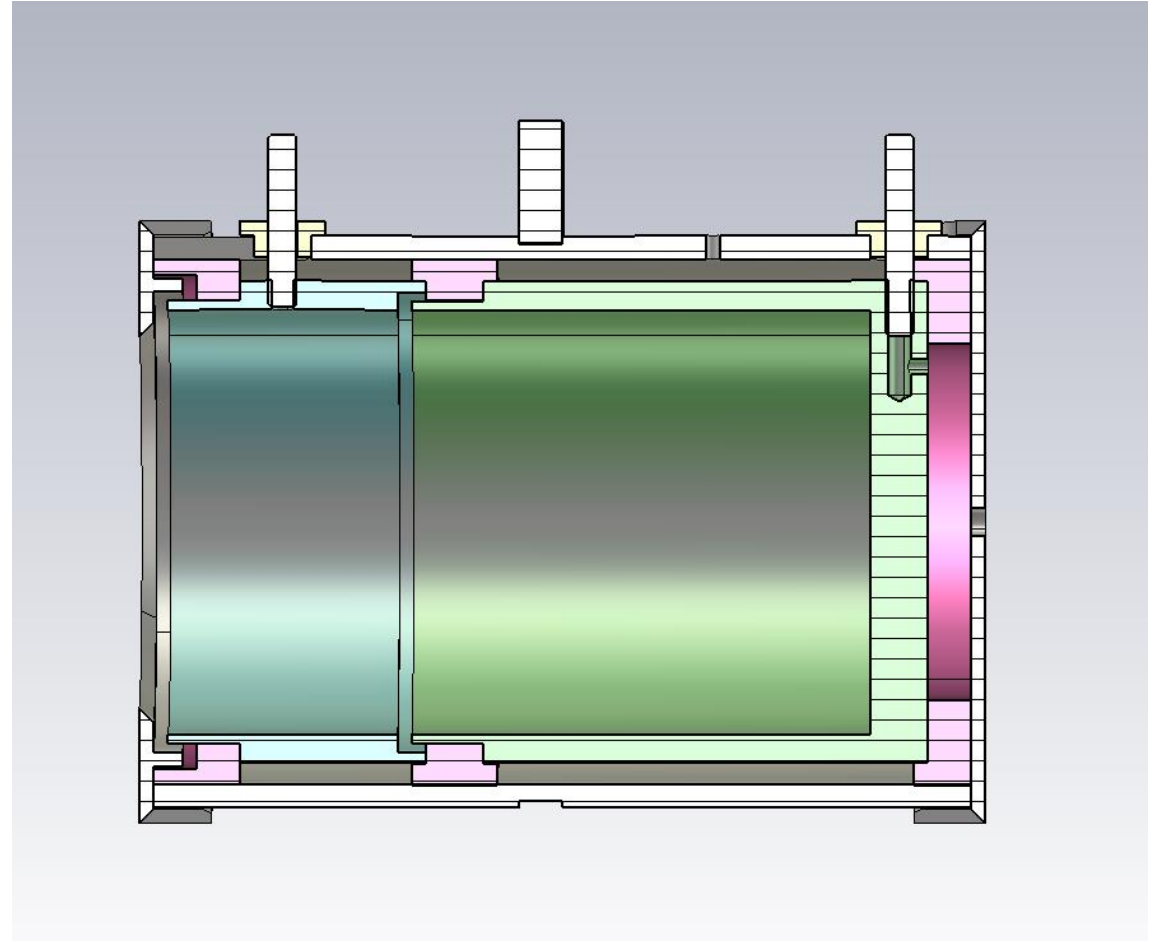
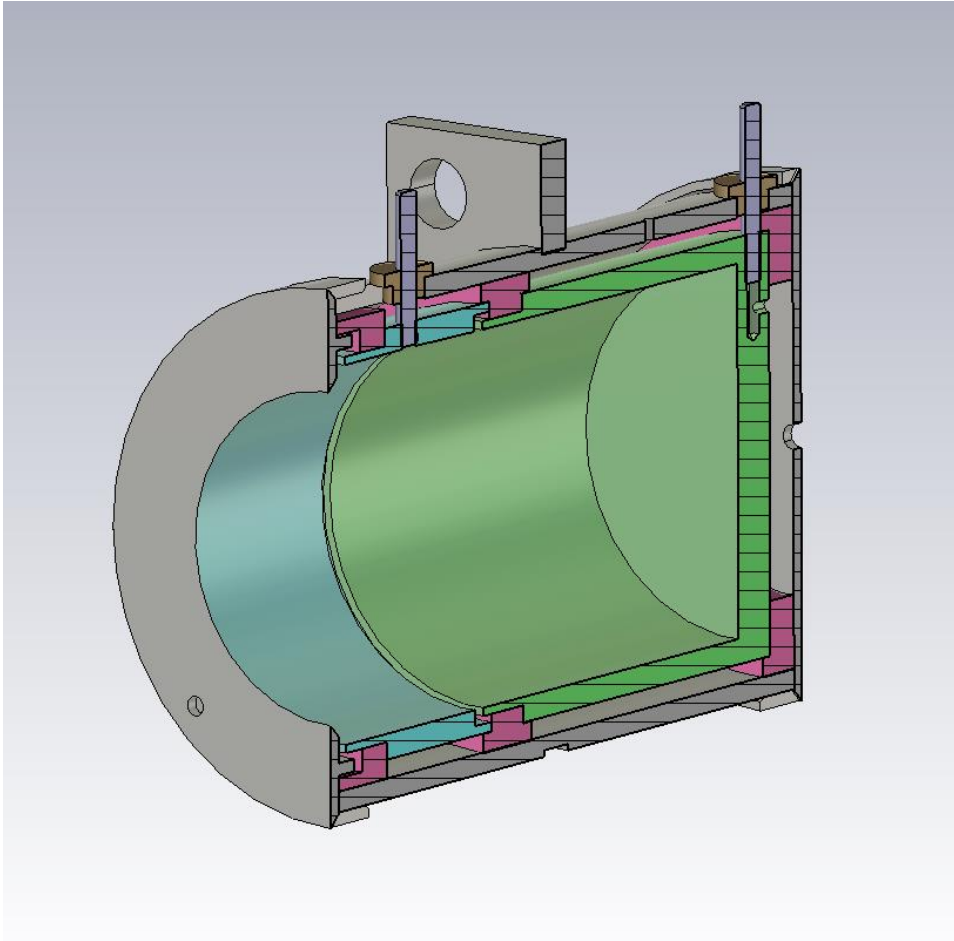
Aperture 60x100 mm



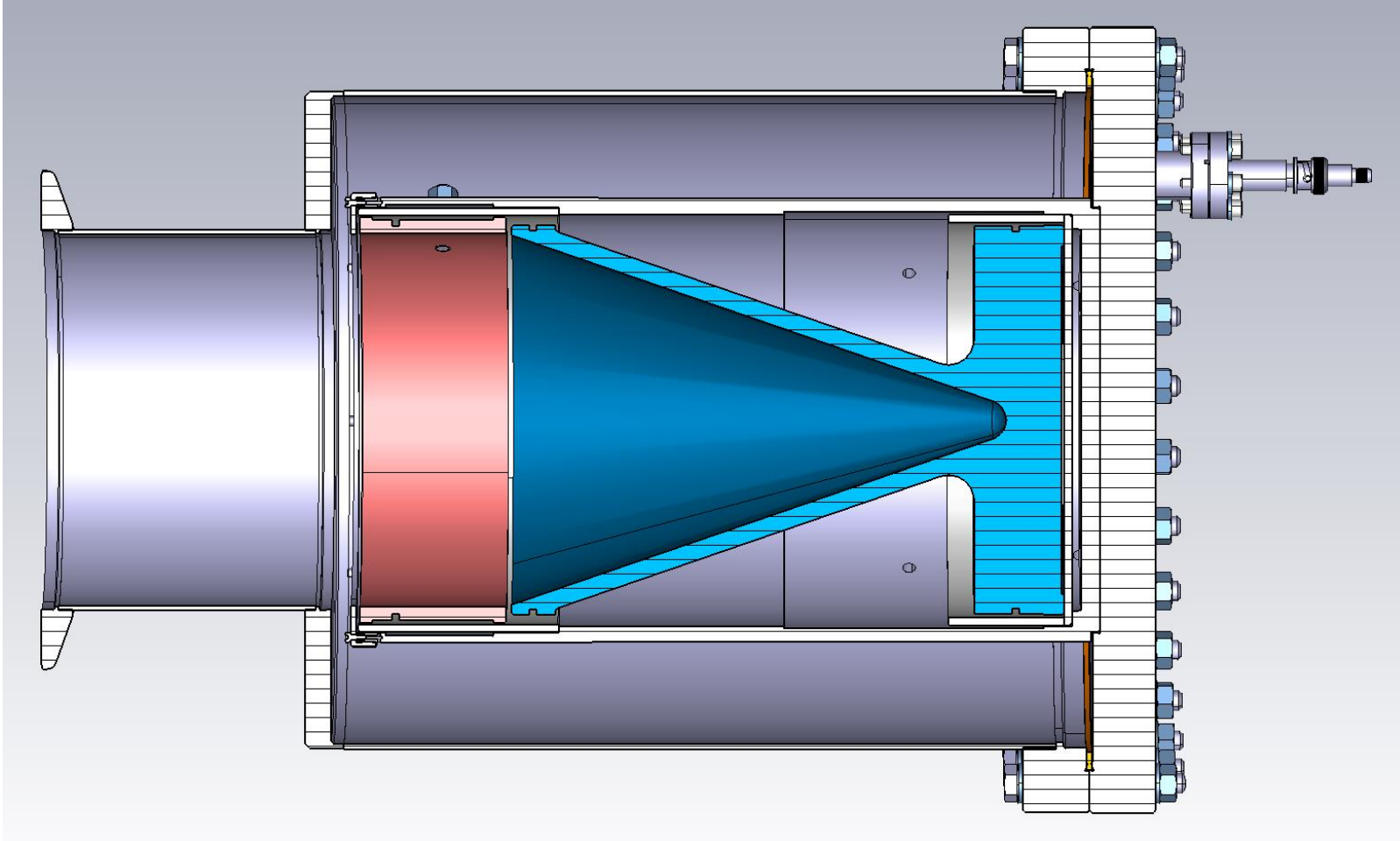
Large aperture – up to 1kV on repeller
Grounded shielding around repeller



FC: Example 2



FC: Example 3



High current/density/energy:

V shape of the FC collector

Coating of the FC collector with refractory metals

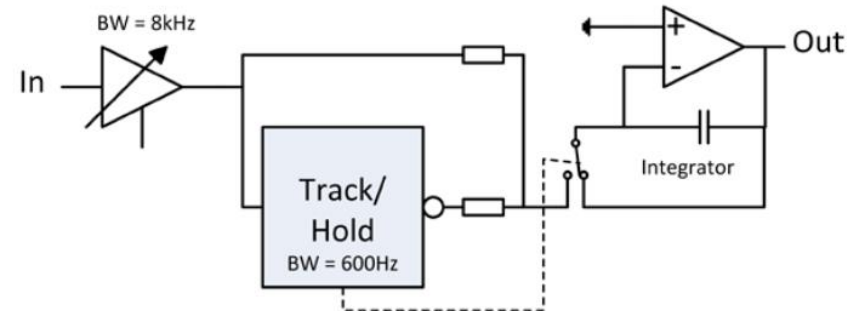
Water cooling

Aperture 140mm

FC: Signal extraction



Microphonic/triboelectric effect /ground loops – proper cables/cabling/connectors are required



Preamplifier (low noise, changeable gain) + ADC

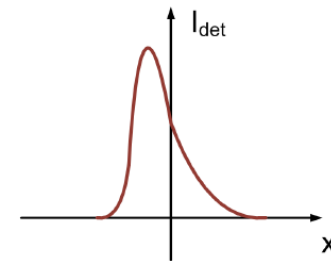
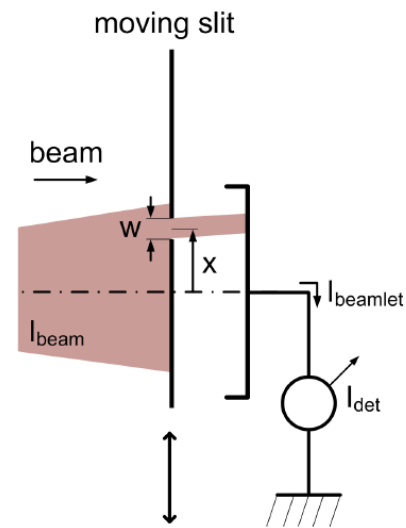
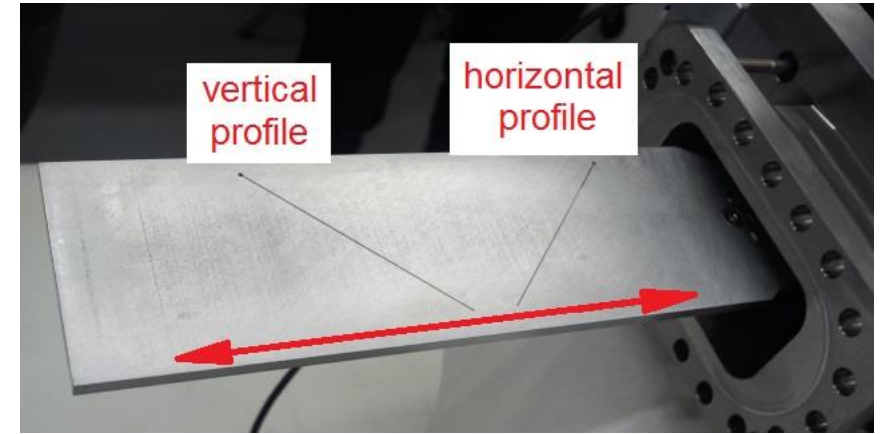
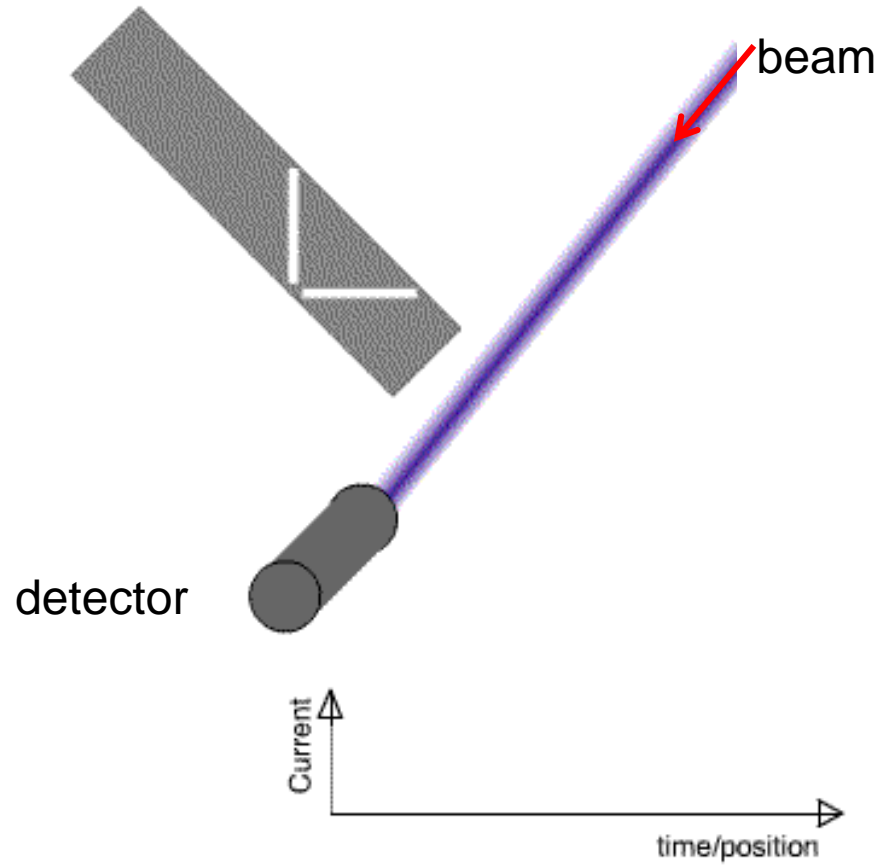
FC: application

Current

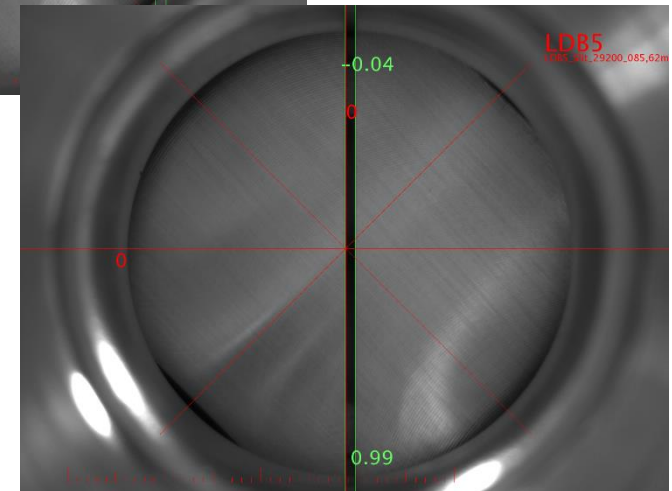
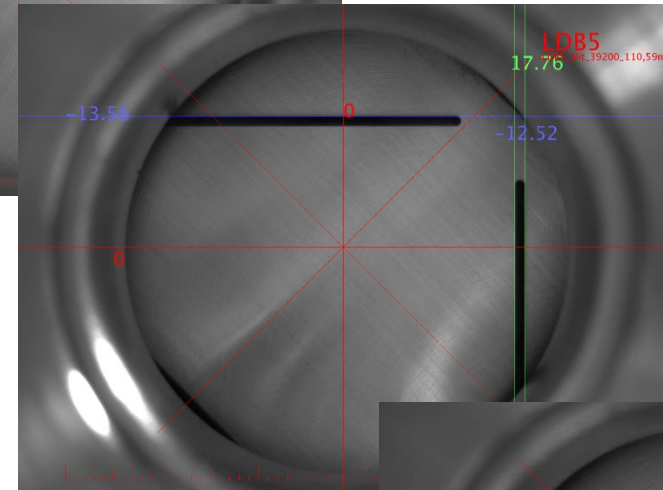
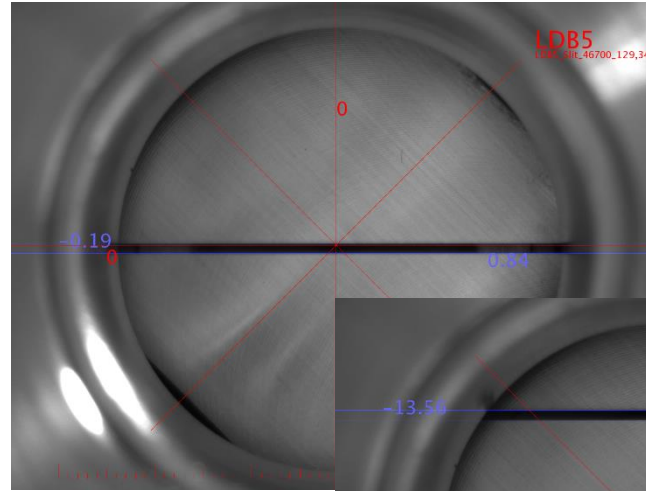
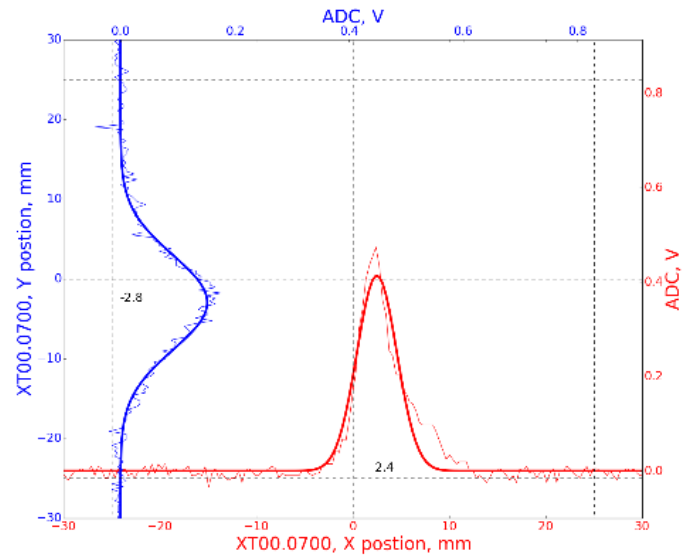
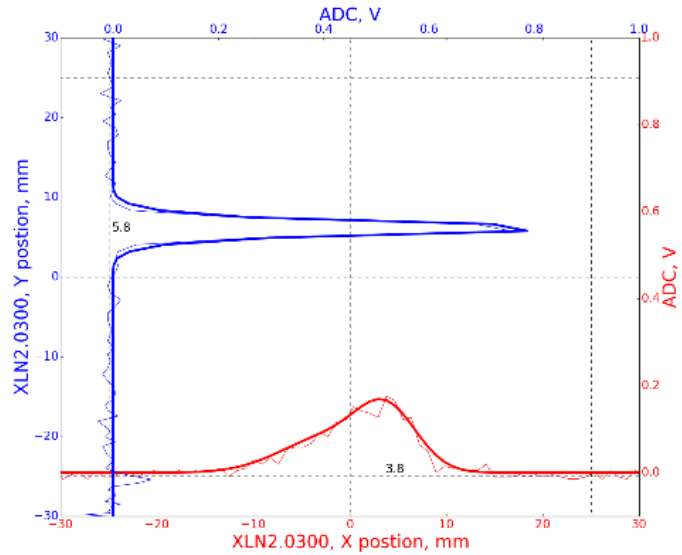
Profile/position

Emittance

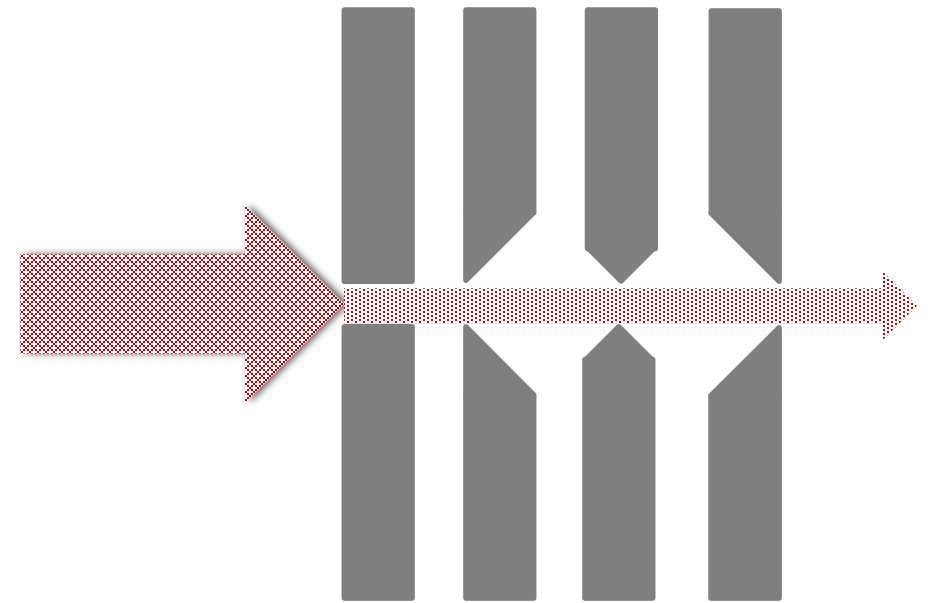
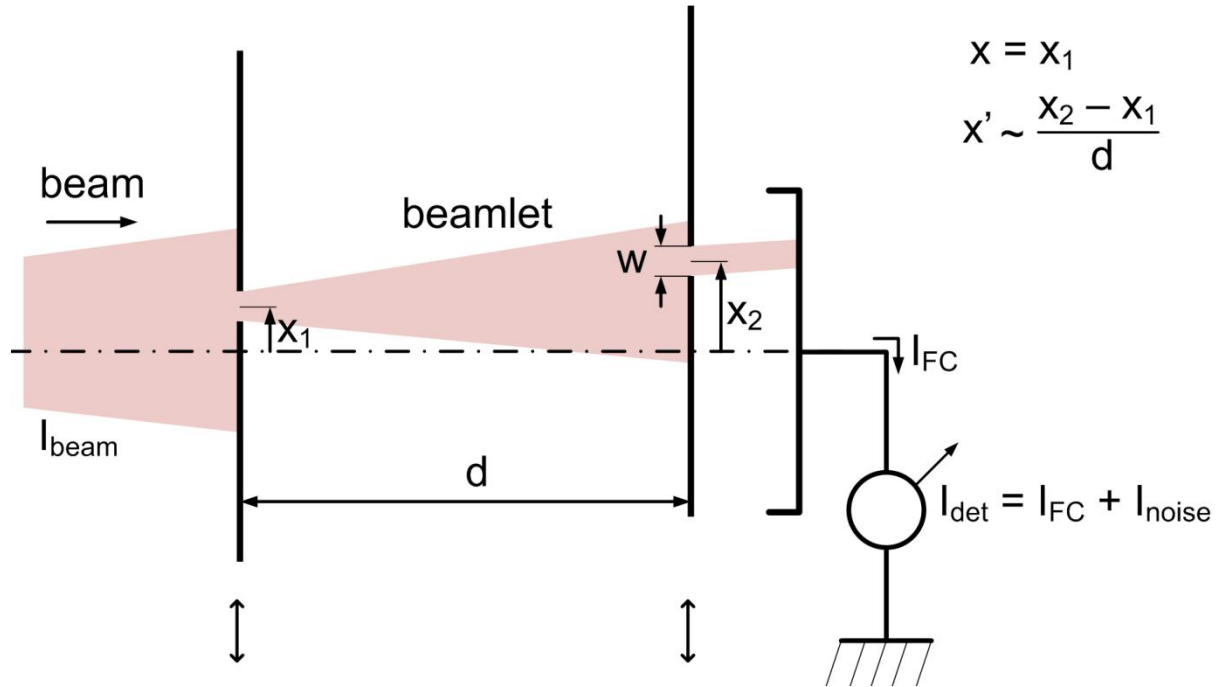
FC and Scanning slit (profile measurement)



FC and Scanning slit (profile measurement)



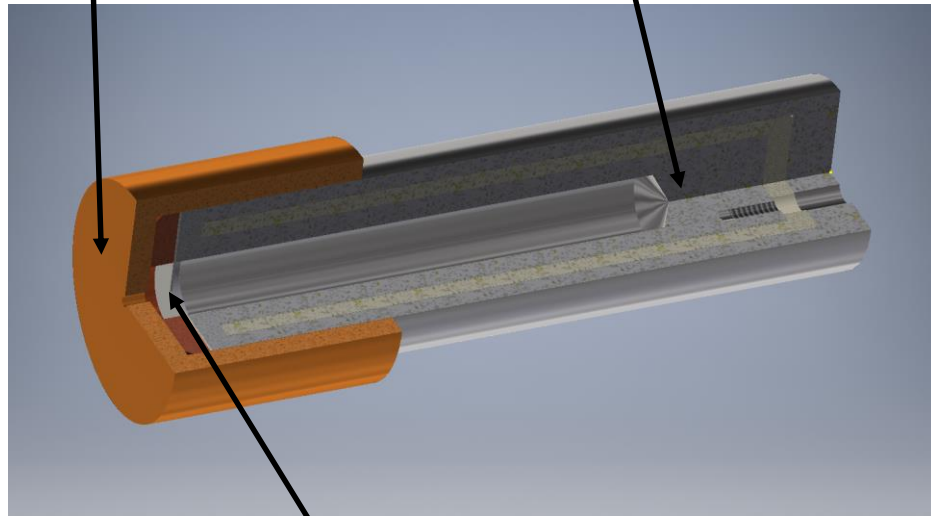
FC and 2 Scanning slits (transverse emittance)



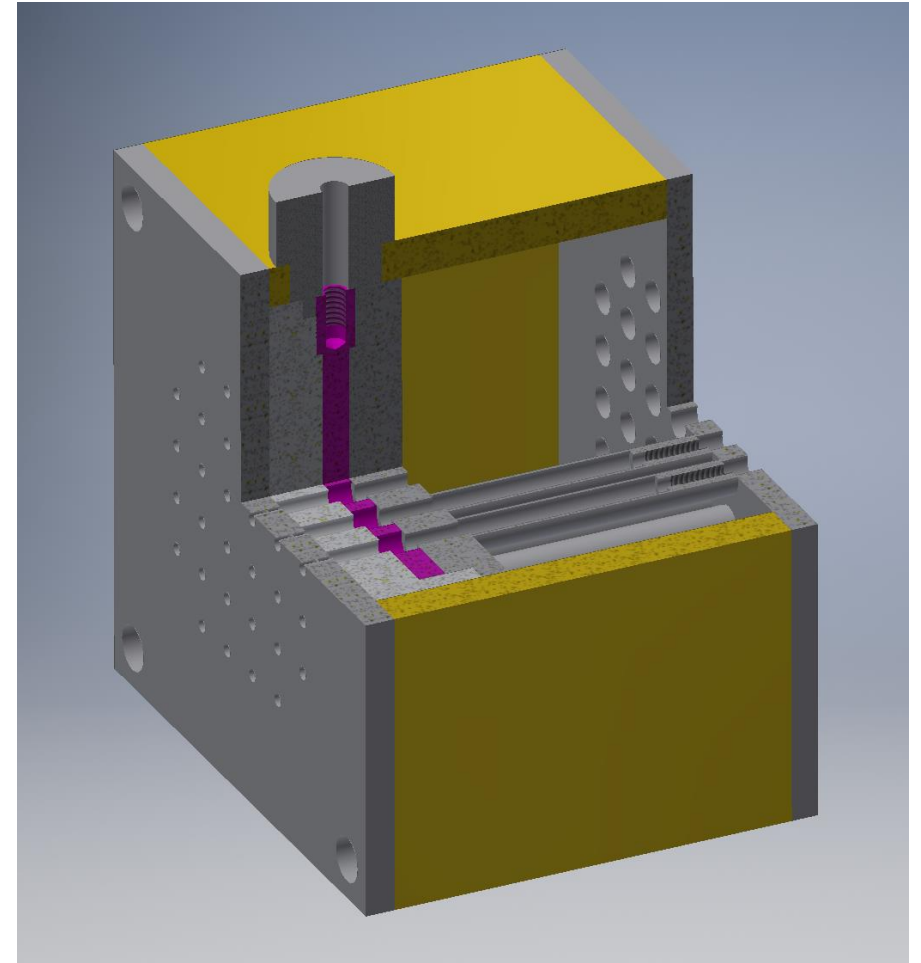
FC: pin-hole / array

1 mm aperture in molybdenum cup

Faraday Cup collector



0.2 mm aperture in tungsten foil



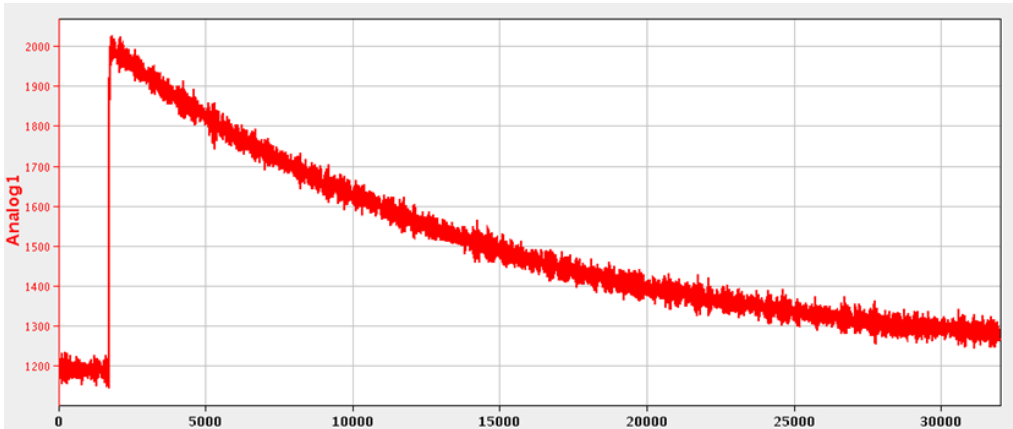
FC: summary

Cheap and robust device for current measurement (< 1 pA), for lower values magic with improving signal to noise ratio is required

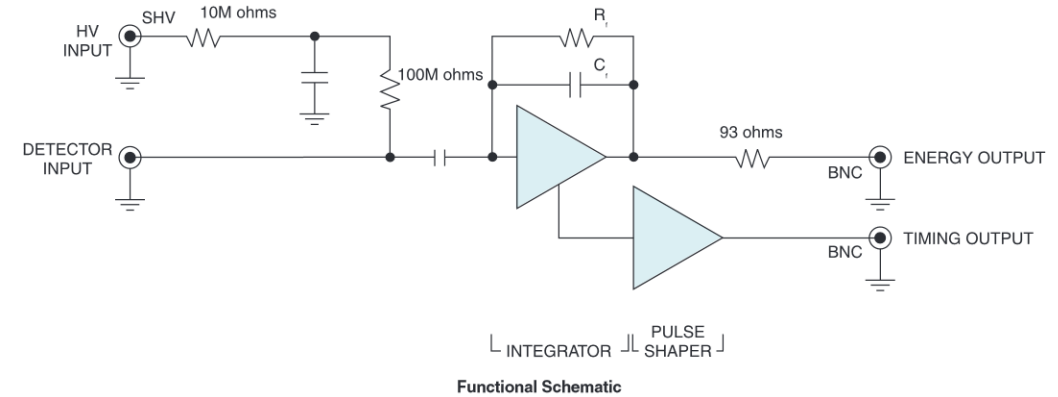
Updated functionality with slit (profile and position measurement)

Beam stopper – energy absorption / dissipation

Silicon detector



Model 2003BT Silicon Detector Preamplifier



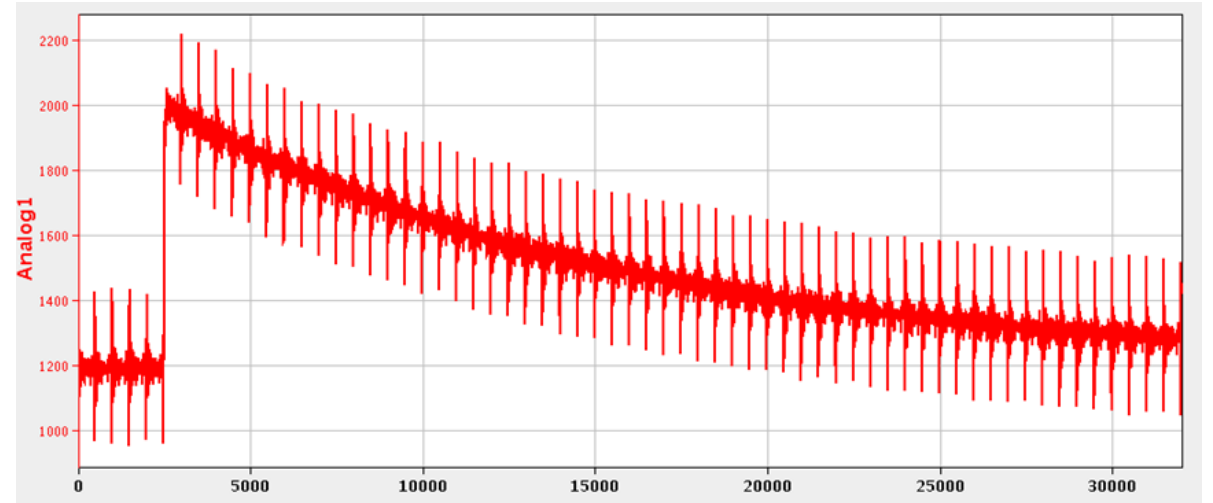
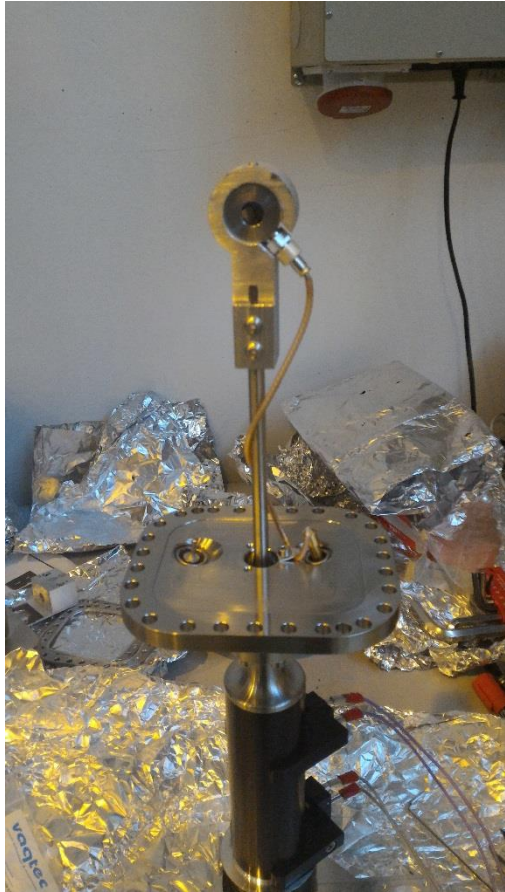
Preamplifier (Operating as a charge to voltage converter) (0.45V per pC -> 20mV per MeV)

500 MeV for 0...10V digitizer

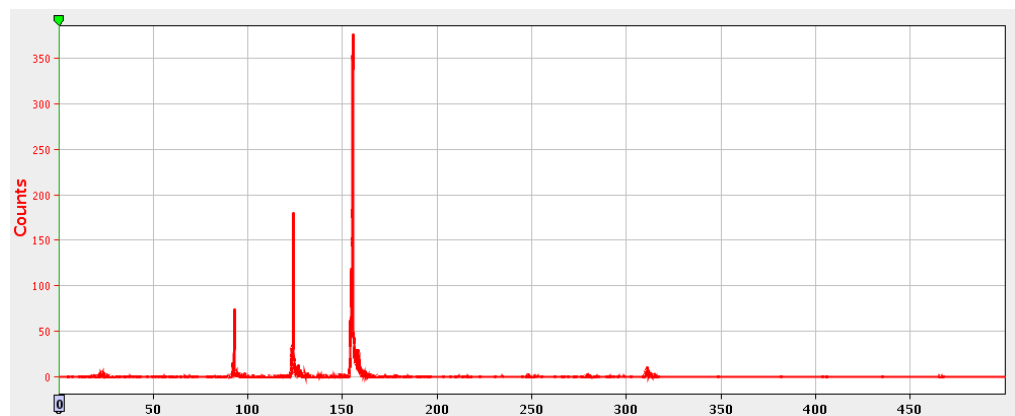
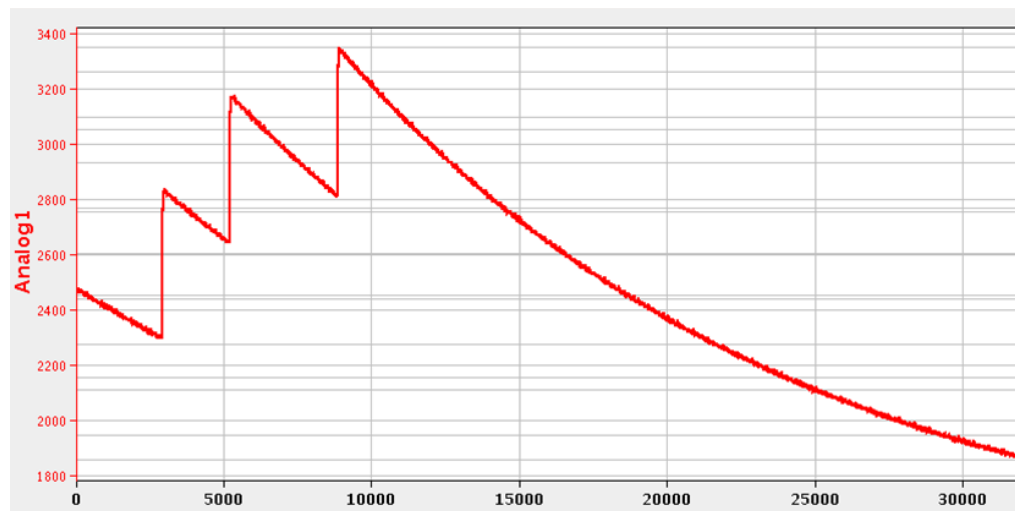
Single particle detection

Fragile/degradation

Silicon detector



Silicon detector

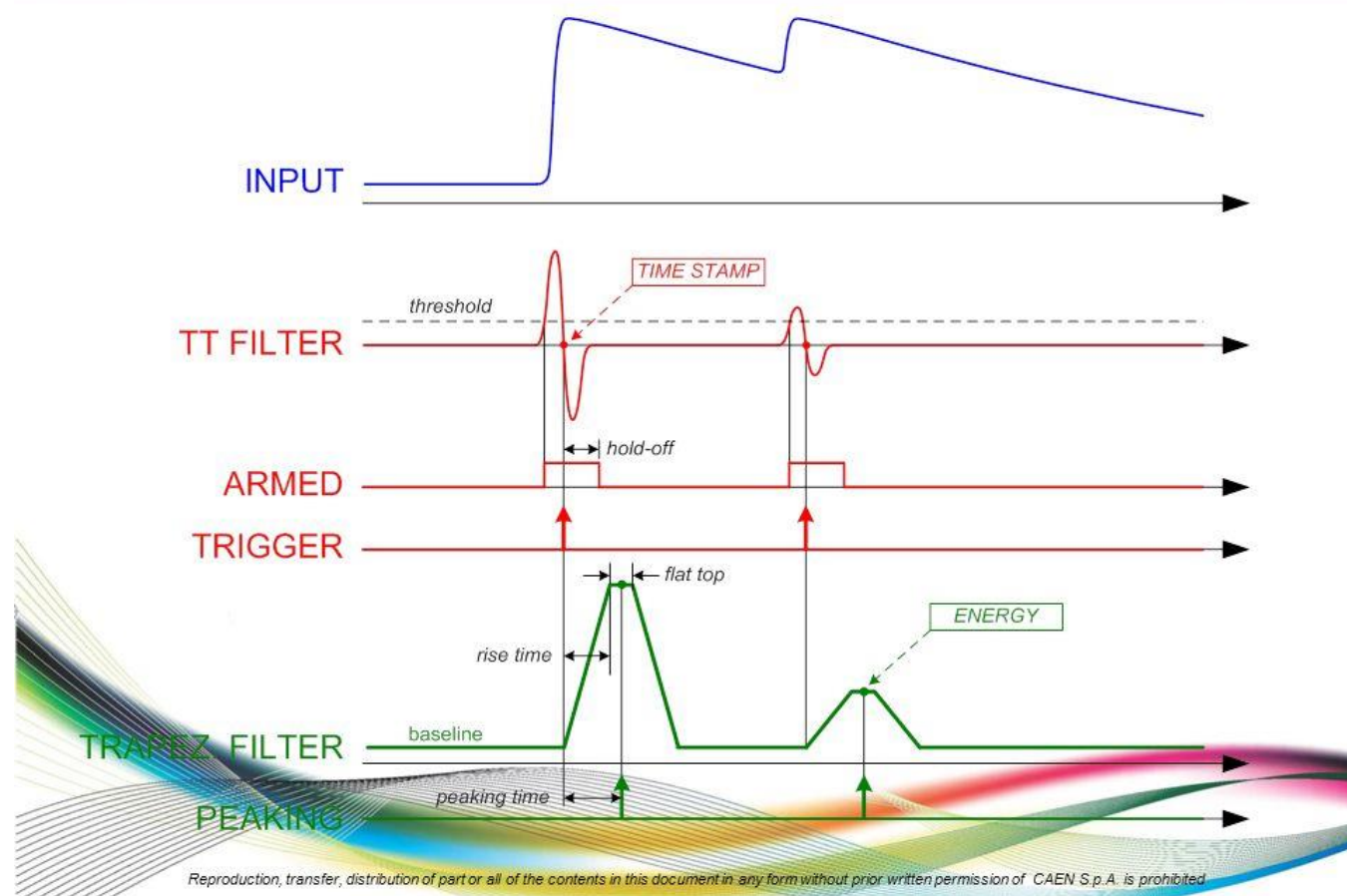


DPP-PHA

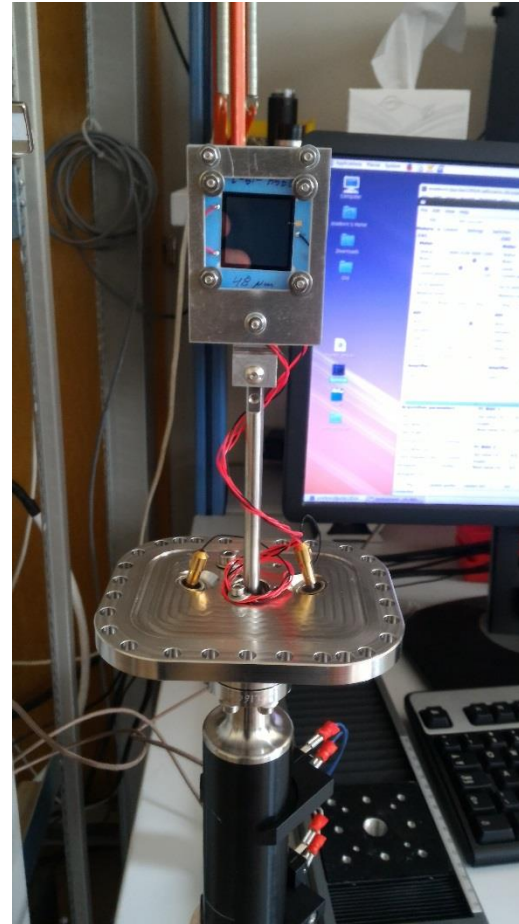
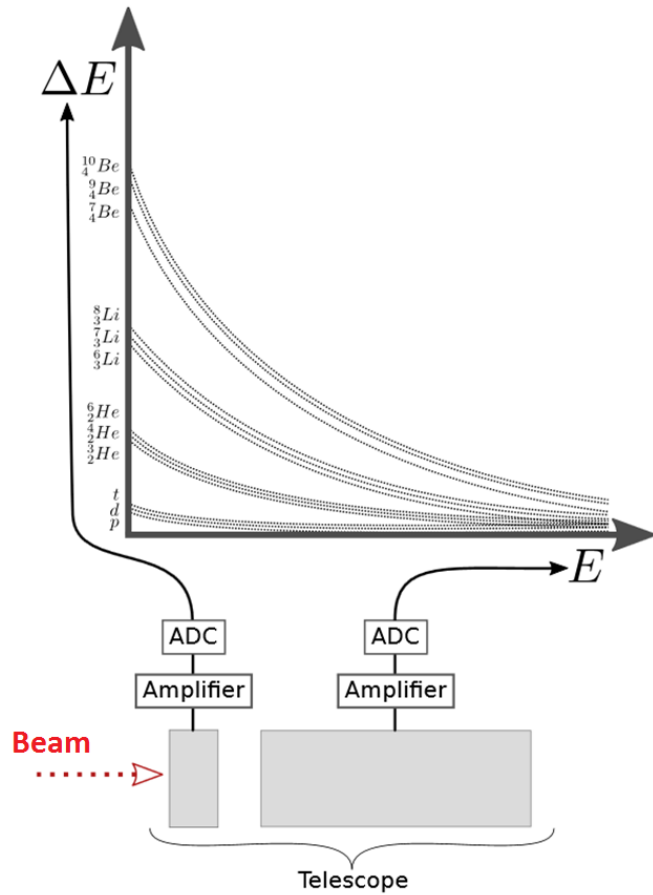
Digital Pulse Processing – Pulse Height Analysis



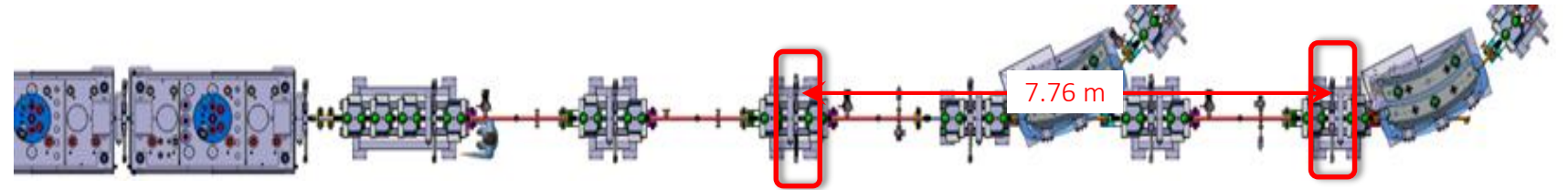
DPP-PHA signals



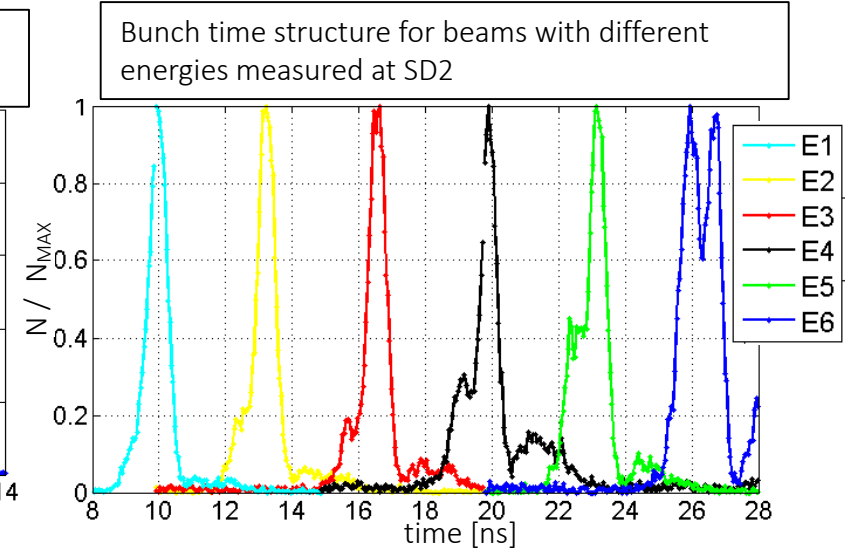
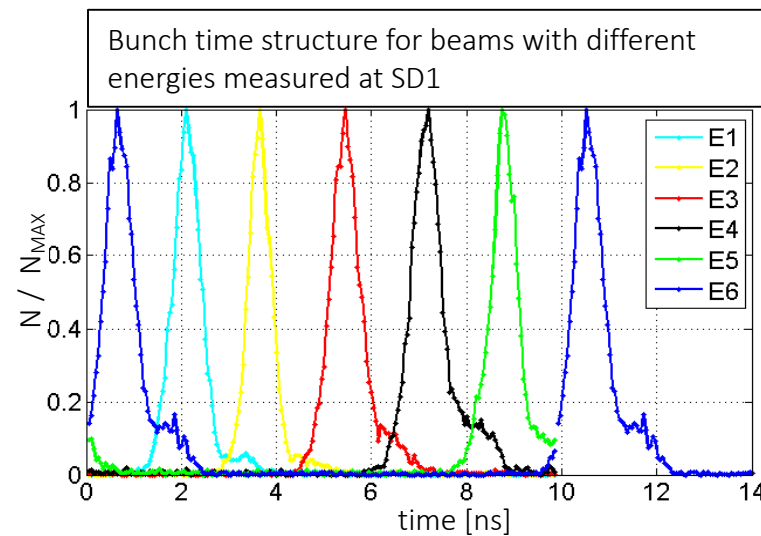
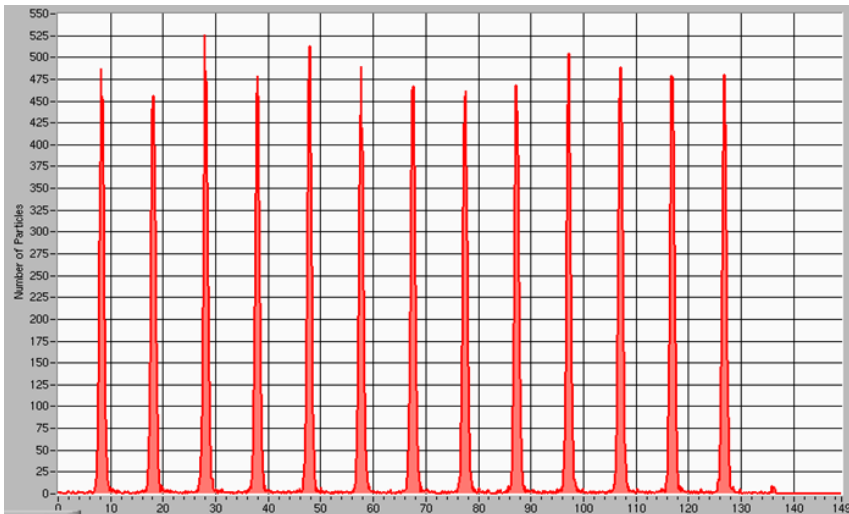
Silicon telescope



Silicon detector: TOF

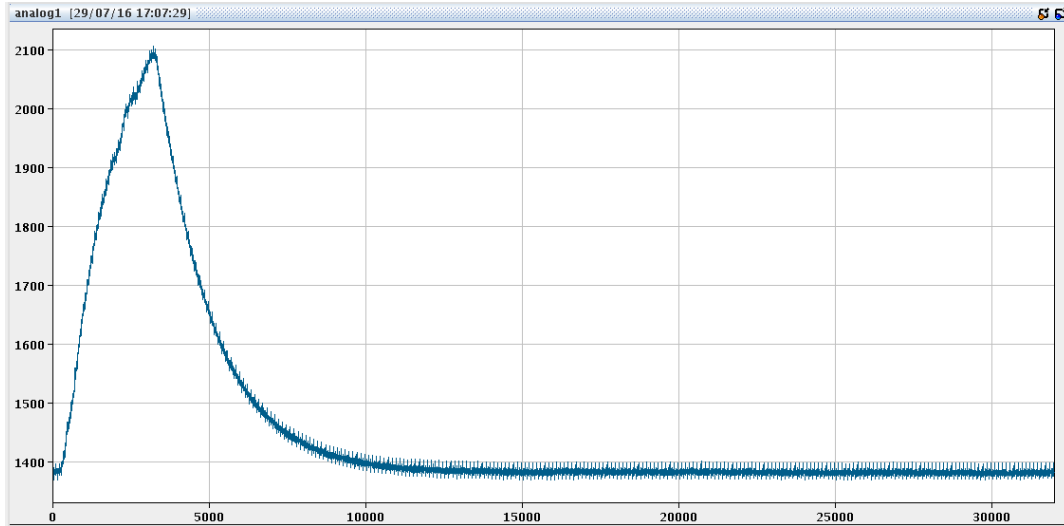


Annular silicon detector



- The TOF system uses the time information provided by two silicon detectors separated 7.76 m from each other
- Energy changes smaller than 0.5 % could be easily resolved
- Bunch structure in second Si detector has partially degraded

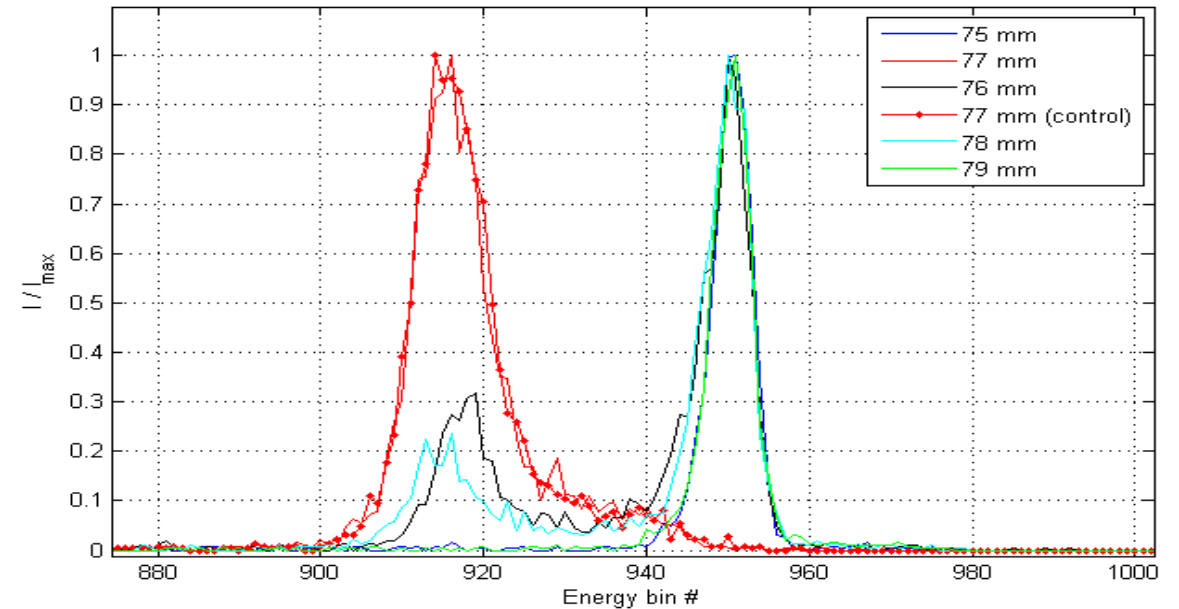
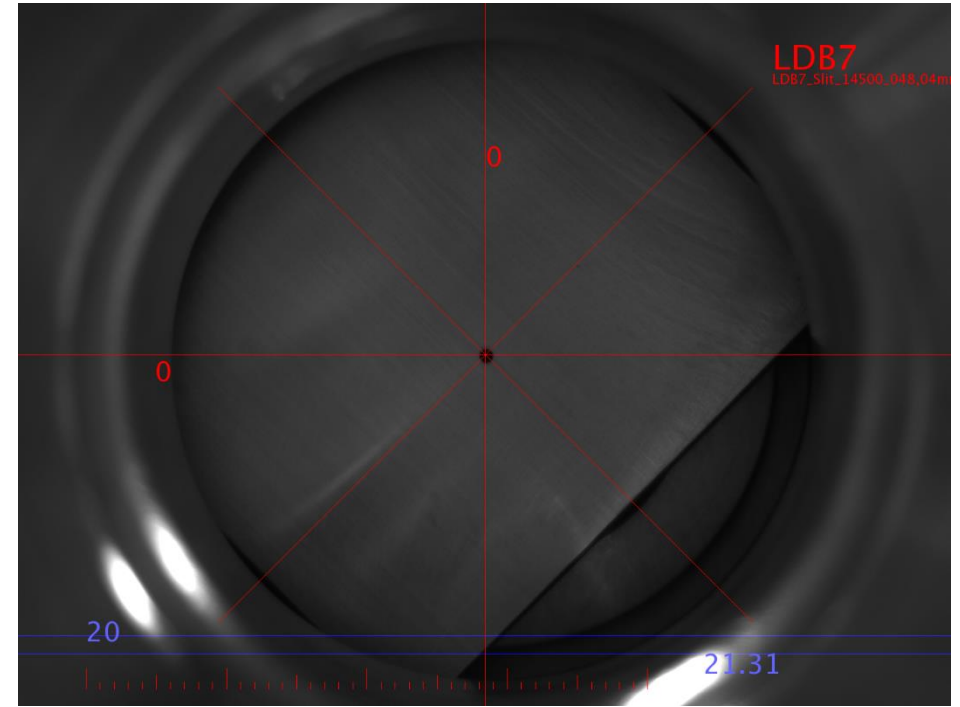
Degradation of SD



Typical leakage current: 2-5 nA

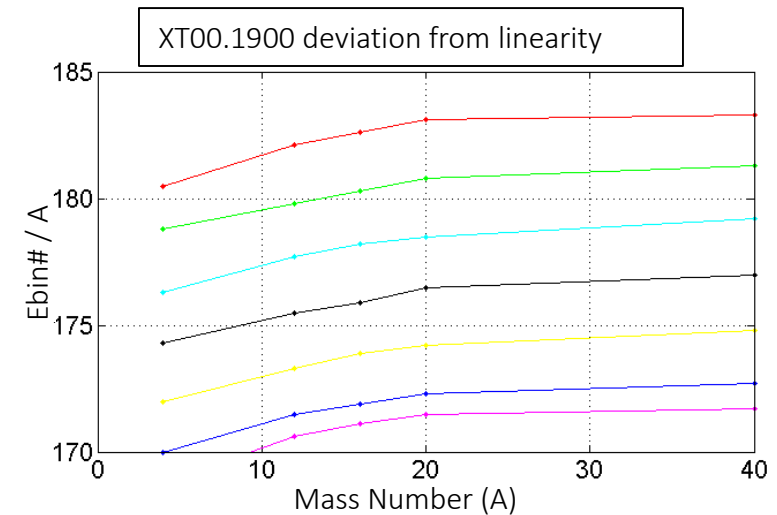
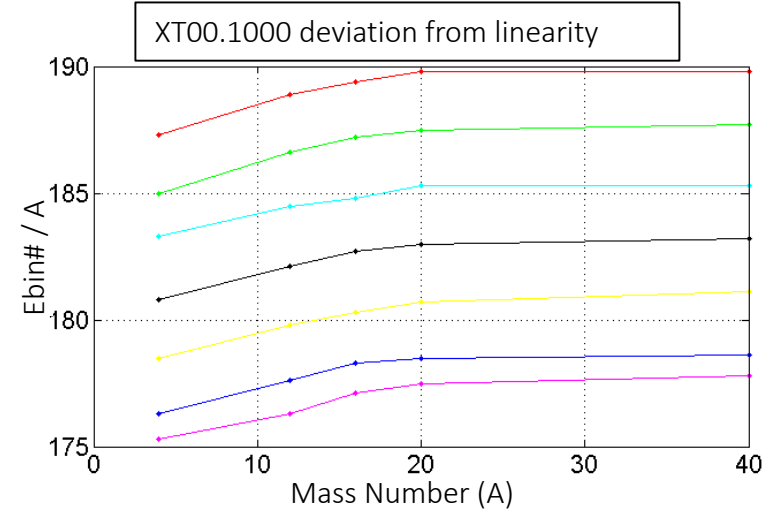
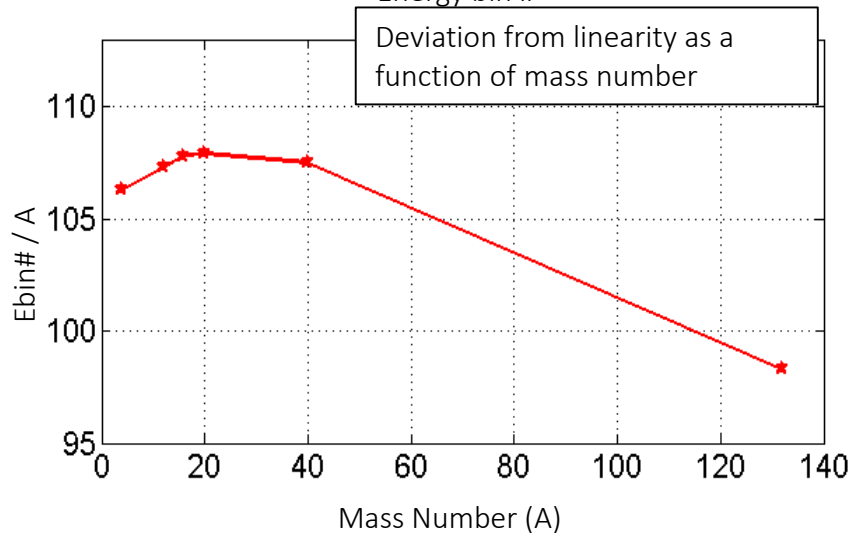
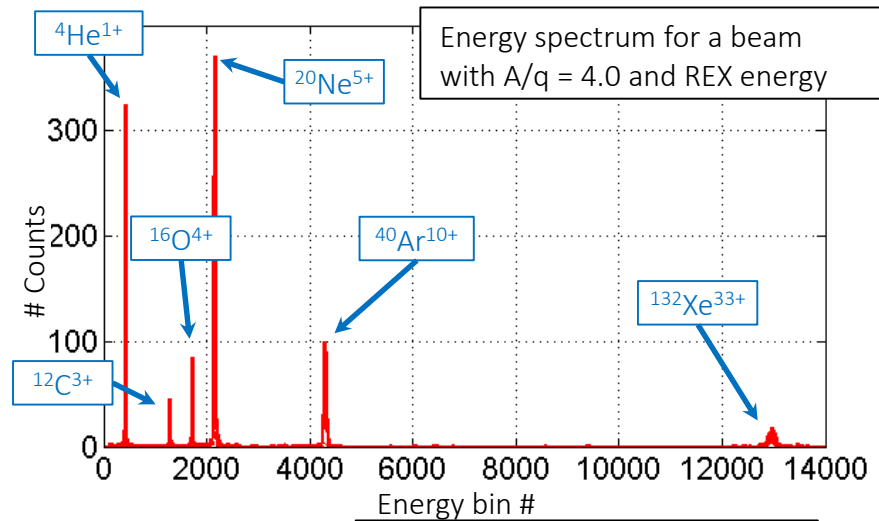
Leakage current increases during operation

Degradation (not critical for relative measurement, can affect final measurements)



Energy measurement: Pulse Height Defect

- Cocktail of beams (EBIS and Xe from GPS target) was sent to silicon detector
- PHD is visible for heavy ions – time of flight technique should be used for energy measurement



Silicon detectors: summary

Absolute energy measurement of the beam (0.5%): roughly measurement using energy output and fine correction using timing output

Single particle detection

Fragile – can be destroyed in one direct pulse

Degradation during operation (corrections for data analysis are required / calibration using alpha source)

Corrections for PHD should be taken into account for data analysis

Scintillators

Widely used for beam profile measurements

- Decay time
- Radiation hardness

For chemical compound $A_m B_n$

$$(-dE/dx)_{A_m B_n} = m(-dE/dx)_A + n(-dE/dx)_B$$

Saturation with very dense beam ($\mu\text{C}/\text{mm}^2$) is possible

Measure the beam profile

- Intercepting methods
 - Scintillating screen
 - Optical transition radiation (OTR)
 - Wire scanner
 - Scraper
- Non intercepting methods
 - Synchrotron radiation
 - Laser wire
 - Rest gas ionisation
 - Beam induced fluorescence
 - Gas jet beam profile monitor

Scintillating screen

- Simply
- Cheap
- Effective

Scintillating materials

Abbreviation	Material	Activator	max. emission	decay time
Quartz	SiO ₂	none	optical	< 10 ns
	CsI	Tl	550 nm	1 μs
Chromolux	ZnS	Ag	450 nm	0.2 μs
	Al ₂ O ₃	Cr	700 nm	100 ns
P43	Li glass	Ce	400 nm	0.1 μs
P46	Gd ₂ O ₂ S	Tb	545 nm	1 ms
P47	Y ₃ Al ₅ O ₁₂	Ce	530 nm	0.3 μs
	Y ₂ Si ₂ O ₅	Ce	400 nm	50 ns

Some example of scintillating light

Al₂O₃, Al₂O₃:Cr, ZrO₂:Mg, Herasil, CsI:Tl, YAG:Ce, P43, Quartz:Ce

Hao Zhang - Beam Diagnostics I (Destructive monitors)

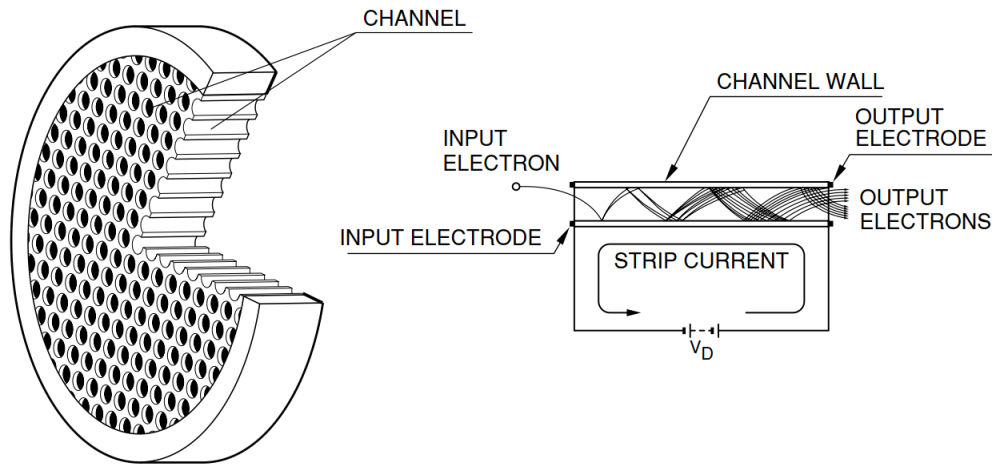
Table 1: Properties of Scintillators

	τ_{decay} [ns]	λ_{max} [nm]	Relative output (NaI:Tl =100)	Radiation hardness [rad]
YAG:Ce	70	550	35	$>10^6$
LYSO:Ce	41	420	75	$>10^6$
BGO	300	480	21	$>10^{5-6}$
Al ₂ O ₃ :Cr ₂ O ₃	> ms	690	Large	High

Scintillator: summary

- Phosphors have very high light yields, but can only be used as thin coating on a rigid support and get damaged very quickly (often used in MCP)
- Normally used for very low intensity beams
- CHROMOX ($\text{Al}_2\text{O}_3:\text{Cr}$, Aluminum Oxide) is a very common choice because it is a very robust ceramic
- ZZZ-doped YAG is also a very frequent choice (fast)

Micro Channel Plate



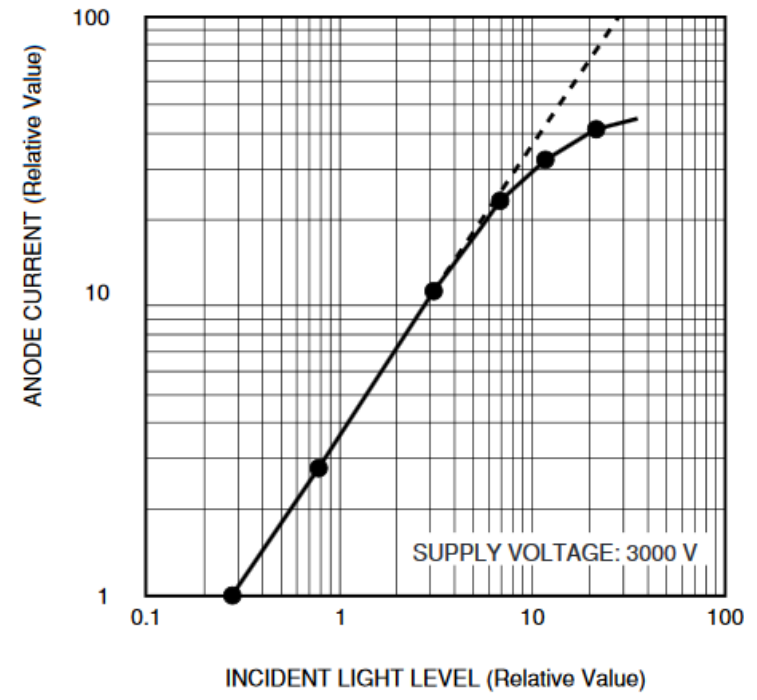
(a) Schematic structure of an MCP

(b) Principle of multiplication

THBV3_1001EA

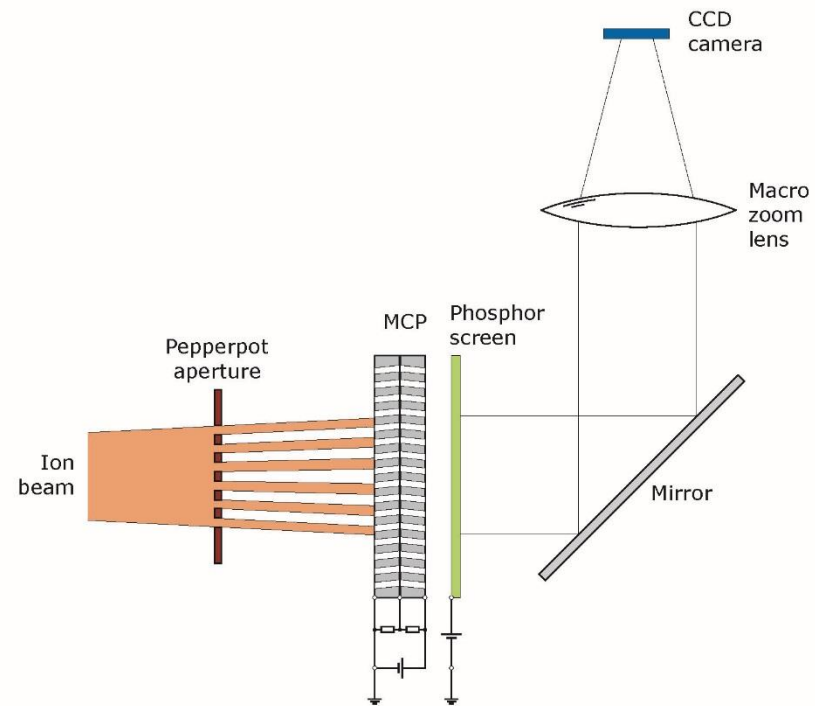
Parameter	Type	F1551				F1094			F1552			F1208-01	F1217		F1942-04	F2395-04	Unit
		-01 [Ⓢ]	-06	-011	-074	-01 [Ⓢ]	-011	-074	-01 [Ⓢ]	-011	-074		-01 [Ⓢ]	-011			
Outer size A		φ 17.9				φ 24.8			φ 32.8			φ 38.4	φ 49.9	φ 86.7	φ 113.9	mm	
Electrode area B		φ 17				φ 23.9			φ 31.8			φ 36.5	φ 49	φ 84.7	φ 112	mm	
Effective area C		φ 14.5				φ 20			φ 27			φ 32	φ 42	φ 77	φ 105	mm	
Thickness D		0.48	0.2	0.48	0.3	0.48	0.3	0.48	0.3	0.48	0.48			1		mm	
Channel diameter		12	4	12	6	12	6	12	6	12	12			25		μm	
Channel pitch		15	5	15	7.5	15	7.5	15	7.5	15	15			31		μm	
Bias angle θ		8		12		8	12	8	12	8	8	12		8		degrees	

Saturation of the MCP (channels)

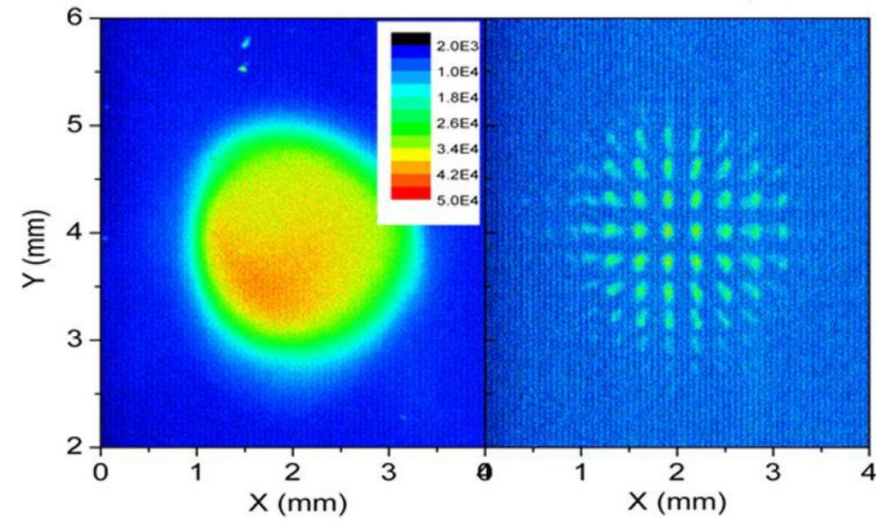


www.hamamatsu.com

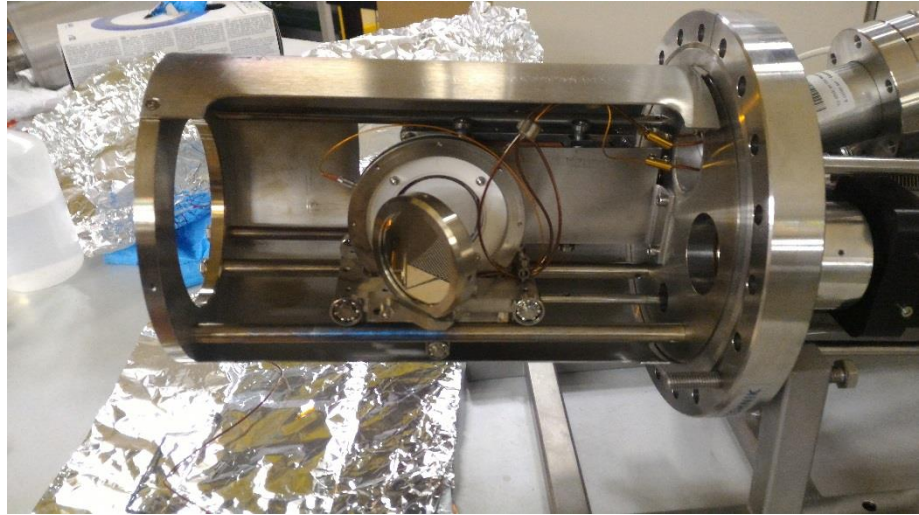
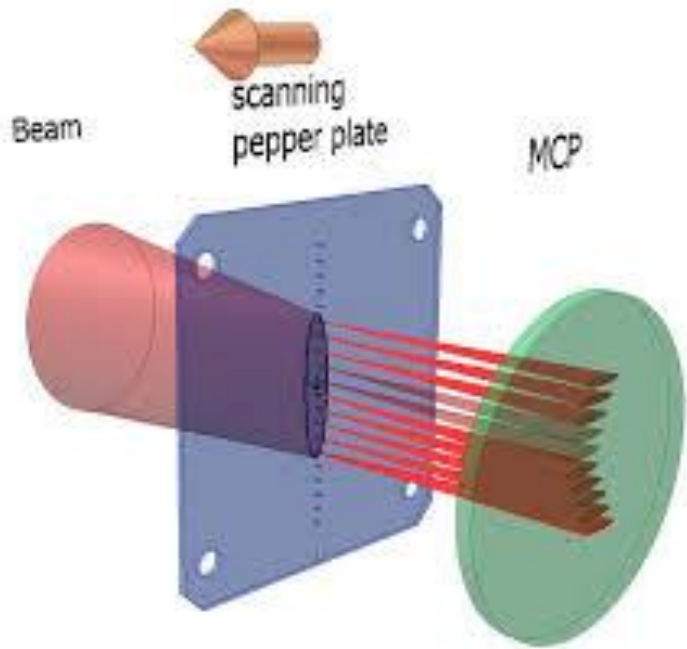
PepperPot



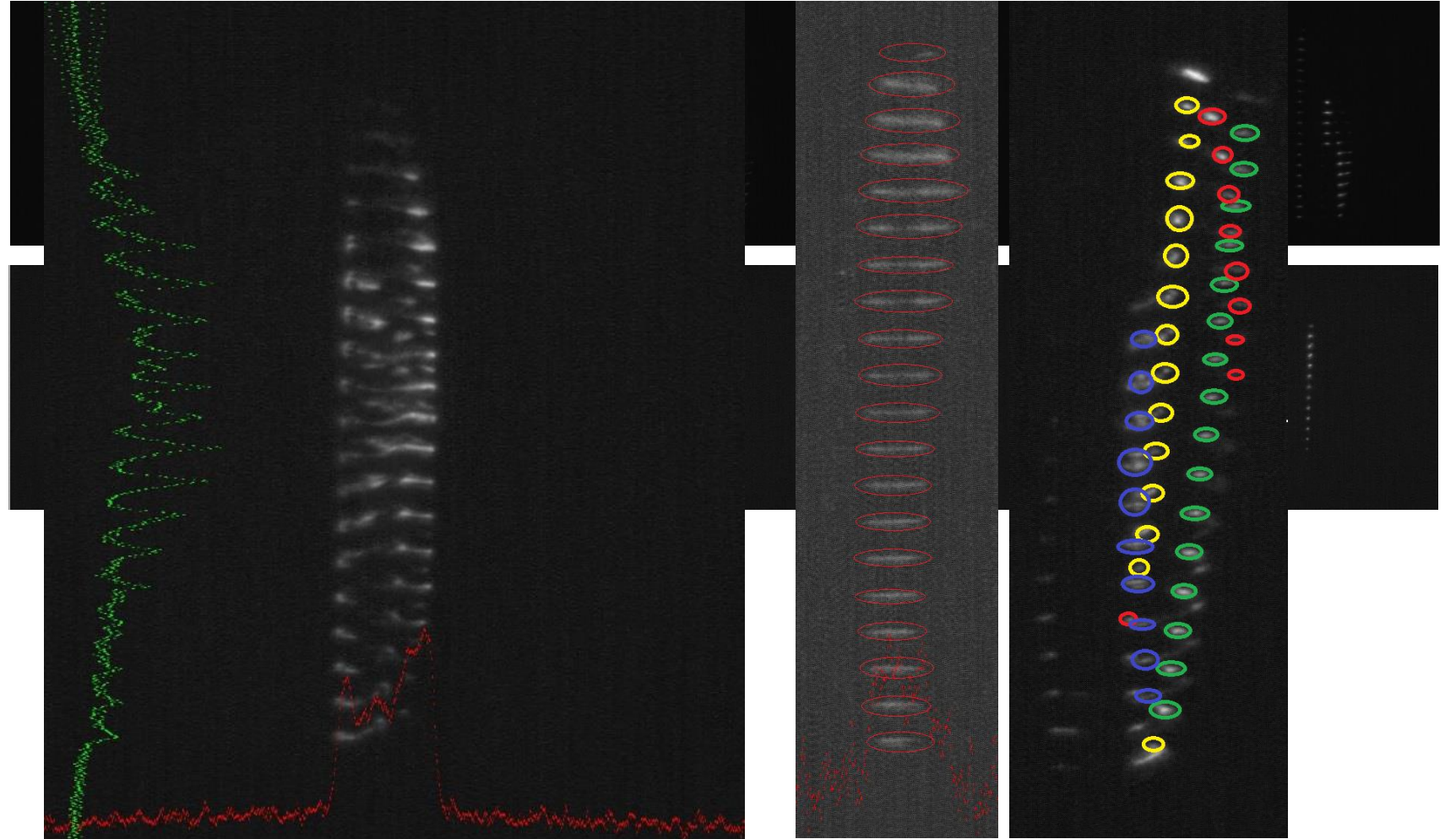
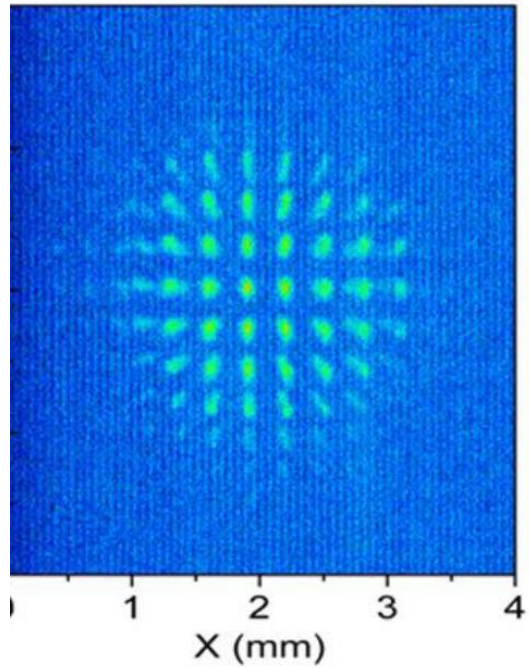
www.dreebit-ibt.com



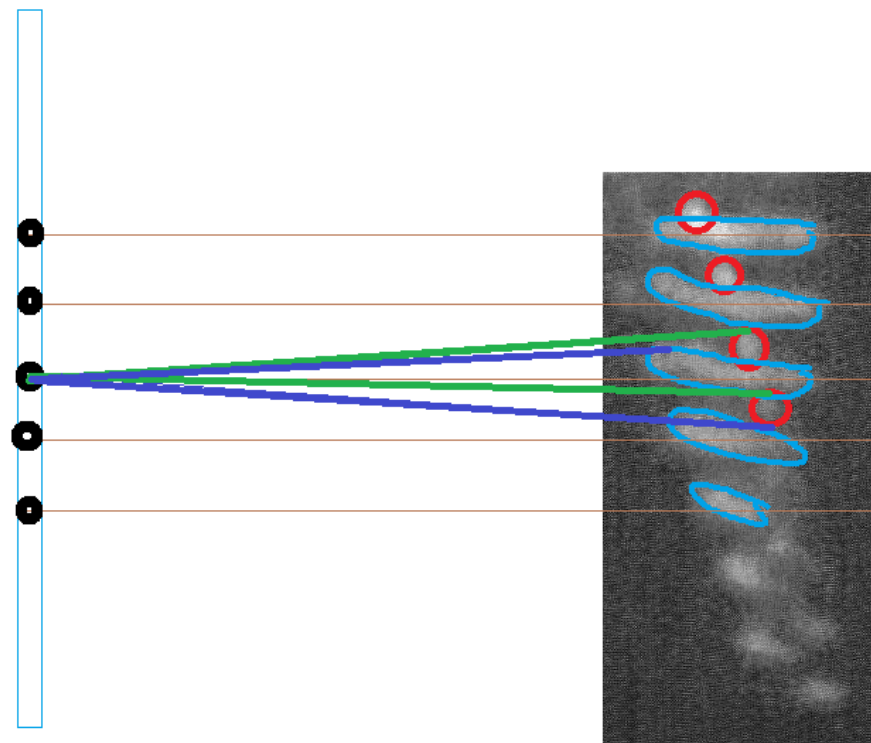
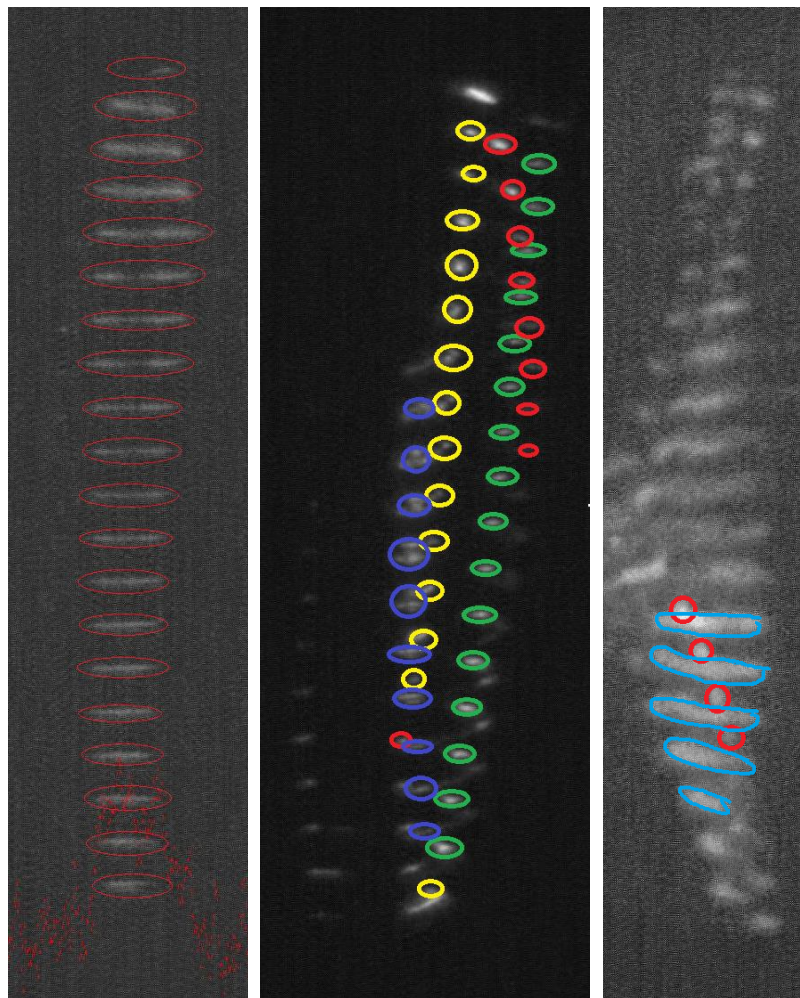
PepperPot: scanning plate



PepperPot: image processing



How to analyze images



MCP summary

Sensitive tool for particles detection

MCP-PMT with a single photon detection

Fragile

Linearity and working point (to avoid saturation)

Image processing can be non-trivial

The End